

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Jatinder Kumar</td> <td>07/06/2011</td> </tr> <tr> <td>David Chong</td> <td>07/06/2011</td> </tr> </tbody> </table>		Name	Execution Date	Jatinder Kumar	07/06/2011	David Chong	07/06/2011
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Jatinder Kumar	07/06/2011						
David Chong	07/06/2011						
RECEIVING PARTY DATA							
Name:	Fairchild Semiconductor Corporation						
Street Address:	3030 Orchard Parkway						
City:	San Jose						
State/Country:	CALIFORNIA						
Postal Code:	95134						
PROPERTY NUMBERS Total: 1							
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13177060</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13177060		
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Application Number:	13177060						
CORRESPONDENCE DATA							
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ATTORNEY DOCKET NUMBER:	0078-010001						
NAME OF SUBMITTER:	Daniel M. Bennett						
Total Attachments: 2 source=0078-010001 Executed Assignment#page1.tif source=0078-010001 Executed Assignment#page2.tif							

OP \$40.00 13177060

ASSIGNMENT

WHEREAS, We, Jatinder Kumar, residing at 306, New Abadi Jallowal, P/O: Bootan Mandi, Jalandhar City, Punjab, India, and David Chong, residing at 12, Lengkok Merbah 1, Taman Bayan, 11900, Bayan Lepas, Penang, Malaysia made certain new and useful inventions and improvements for which we filed an application for Letters Patent of the United States entitled CONDUCTIVE CHIP DISPOSED ON LEAD SEMICONDUCTOR PACKAGE AND METHODS OF MAKING THE SAME;

WHEREAS, We hereby authorize and request our attorneys, as listed on the Combined Declaration and Power of Attorney, at Brake Hughes Bellermann LLP, to insert here in parentheses (Ser. No. 13/177,060 ; Filing Date: July 6, 2011) the filing date and application number of said application when known.

AND WHEREAS, Fairchild Semiconductor Corporation, a corporation organized and existing under and by virtue of the laws of the State of Delaware, and having an office and place of business at 3030 Orchard Parkway, San Jose, California 95134 (hereinafter "Assignee"), is desirous of acquiring the entire right, title and interest in and to said inventions, improvements and application and in and to the Letters Patent to be obtained therefore;

NOW, THEREFORE, to all whom it may concern, be it known that for good and valuable consideration, the receipt and sufficiency whereof is hereby acknowledged, we have sold, assigned, and transferred, and by these presents do sell, assign and transfer unto said Assignee, its successors or assigns, the entire right, title and interest for all countries in and to all inventions and improvements disclosed in the aforesaid application, and in and to the said application, all divisions, continuations, continuations-in-part, or renewals thereof, all Letters Patent which may be granted there from, and all reissues or extensions of such patents, and in and to any and all applications which have been or shall be filed in any foreign countries for Letters Patent on the said inventions and improvements, including an assignment of all rights under the provisions of the International Convention, and all Letters Patent of foreign countries which may be granted there from; and we do hereby authorize and request the Commissioner of

Patents and Trademarks to issue any and all United States Letters Patent for the aforesaid inventions and improvements to the said Assignee as the assignee of the entire right, title and interest in and to the same, for the use of the said Assignee, its successors and assigns.

AND, for the consideration aforesaid, we do hereby agree that we and my executors and legal representatives will make, execute and deliver any and all other instruments in writing including any and all further application papers, affidavits, assignments and other documents, and will communicate to said Assignee, its successors and representatives all facts known to me relating to said improvements and the history thereof and will testify in all legal proceedings and generally do all things which may be necessary or desirable more effectually to secure to and vest in said Assignee, its successors or assigns the entire right, title and interest in and to the said improvements, inventions, applications, Letters Patent, rights, titles, benefits, privileges and advantages hereby sold, assigned and conveyed, or intended so to be.

AND, furthermore, we covenant and agree with said Assignee, its successors and assigns, that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by me and that full right to convey the same as herein expressed is possessed by me.

IN TESTIMONY WHEREOF, I have hereunto set my hand this 6th day of July, 2011.



Jatinder Kumar

IN TESTIMONY WHEREOF, I have hereunto set my hand this 6th day of July, 2011.



David Chong